

PART INFORMATION

Mfg Item Number	MC68HC705C8AB
Mfg Item Name	PSDIP 42

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2013-06-14
Response Document ID	6013K00085D001A1.9
Contact Name	Freescale Semiconductor Inc
Contact Title	Product Technical Support
Contact Phone	1-800-521-6274
Contact Email	support@freescale.com
Authorized Representative	Daniel Binyon
Representative Title	EPP Customer Response
Representative Phone	512-895-3406
Representative Email	eppanlst@freescale.com
URL for Additional Information	www.freescale.com

DECLARATION

EU RoHS	No
Pb Free	No
HalogenFree	No
Plating Indicator	e0
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MC68HC705C8AB
Mfg Item Name	PSDIP 42
Version	ALL
Weight	4.389450
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	
Peak Processing Temperature	
Max Time at Peak Temperature	
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	2 - Item(s) contain RoHS restricted substances above the limits and is not under exemptions
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemptions in this part	
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

SubPart	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	REACHPPM	REACH%
Epoxy Die Attach	0.0024						g				
Epoxy Die Attach		Metals	Cadmium, metal	7440-43-9		0	g	3	0.0003	0	0
Epoxy Die Attach		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.000331	g	137740	13.774	75	0.0075
Epoxy Die Attach		Metals	Lead, metallic lead and lead alloys	7439-92-1		0	g	7	0.0007	0	0
Epoxy Die Attach		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.000073	g	30303	3.0303	16	0.0016
Epoxy Die Attach		Metals	Silver, metal	7440-22-4		0.001996	g	831947	83.1947	454	0.0454
Die Encapsulant	3.2556						g				
Die Encapsulant		Flame Retardants	Antimony trioxide	1309-64-4		0.036593	g	11240	1.124	8336	0.8336
Die Encapsulant		Solvents, additives, and other materials	Tetraphenylphosphonium tetraphenylborate	15525-15-2		0.007319	g	2248	0.2248	1667	0.1667
Die Encapsulant		Flame Retardants	Bromophenol, formaldehyde, epichlorohydrin polymer	68541-56-0		0.086492	g	26567	2.6567	19704	1.9704
Die Encapsulant		Plastics/polymers	Ortho-Cresol, Polymer with 1-Chloro-2,3-Epoxypropane and Formaldehyde	29690-82-2		0.365923	g	112398	11.2398	83365	8.3365
Die Encapsulant		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.009148	g	2910	0.291	2084	0.2084
Die Encapsulant		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000042	g	13	0.0013	0	0.0009
Die Encapsulant		Solvents, additives, and other materials	[3,4-Epoxy(2-cyclohexylethyl)trimethoxysilane	3388-04-3		0.118758	g	36478	3.6478	27055	2.7055
Die Encapsulant		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.236187	g	72548	7.2548	53807	5.3807
Die Encapsulant		Glass	Silica, vitreous	80676-86-0		2.395138	g	735698	73.5698	545666	54.5666
Bonding Wire	0.0017						g				
Bonding Wire		Metals	Gold, metal	7440-57-5		0.0017	g	1000000	100	387	0.0387
Copper Lead Frame	1.0489						g				
Copper Lead Frame		Metals	Copper, metal	7440-50-8		1.011993	g	963955	96.3955	230348	23.0348
Copper Lead Frame		Solvents, additives, and other materials	Phosphorus	7723-14-0		0.000865	g	825	0.0825	197	0.0197
Copper Lead Frame		Metals	Iron, metal	7439-89-6		0.024449	g	23500	2.35	5615	0.5615
Copper Lead Frame		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.000178	g	170	0.017	40	0.004
Copper Lead Frame		Metals	Silver, metal	7440-22-4		0.010489	g	10000	1	2389	0.2389
Copper Lead Frame		Metals	Tin, metal	7440-31-5		0.000315	g	300	0.03	71	0.0071
Copper Lead Frame		Metals	Zinc, metal	7440-66-6		0.001311	g	1250	0.125	298	0.0298
Silicon Semiconductor Die	0.01245						g				
Silicon Semiconductor Die		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000249	g	20000	2	56	0.0056
Silicon Semiconductor Die		Glass	Silicon, doped	-		0.012201	g	980000	98	2779	0.2779
Lead Frame Plating	0.0684						g				
Lead Frame Plating		Metals	Lead, metallic lead and lead alloys	7439-92-1		0.01368	g	200000	20	3116	0.3116
Lead Frame Plating		Metals	Tin, metal	7440-31-5		0.05472	g	800000	80	12466	1.2466

LINKS

MCD LINK

Freescale website <http://www.freescale.com>

GENERAL ENVIRONMENTAL COMPLIANCE LINKS

RoHS signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ROHS_Freescale_Response.pdf

China RoHS <http://www.freescale.com/chinarohs>

REACH signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_REACH_Freescale_Response.pdf

ELV signed letter http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_ELV_Freescale_Reponse.pdf

Conflict Minerals statement http://www.freescale.com/files/abstract/corporate/ehs_epp/ENV_CONFLICT_METAL_Freescale_Response.pdf

FREESCALE ENVIRONMENTAL INFORMATION

EPP website <http://www.freescale.com/epp>

FAQ http://www.freescale.com/webapp/sps/site/overview.jsp?code=ENVIRON_FAQ

Technical Service Request https://www.freescale.com/webapp/servicerequest.create_SR.framework?defaultCategory=Hardware Product Support&defaultTopic=Environmentally Preferred Prod

LINKS TO BLANK IPC1752 FORMS

Blank IPC1752 v0.9 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v0.9_MCD_Template.pdf

Blank IPC1752 v1.1 Form http://www.freescale.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MC68HC705C8AB_IPC1752_v09.xml

http://www.freescale.com/mcdfs/MC68HC705C8AB_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MC68HC705C8AB_IPC1752A.xml